BAREBONE XPC cube SH570R8

SUPPORTS 10TH/11TH GENERATION INTEL CORE PROCESSORS AND FOUR HARD DISKS

The Shuttle XPC cube Barebone SH570R8 is able to accommodate up to four 3.5 inch hard drives for enormous storage capacity - ideal for both home and commercial applications. However, this barebones platform is way more than just about storage - the SH570R8 has enough grunt under its aluminium bonnet to be a high-end gaming PC or a workstation for intensive graphics or even video applications. Its black-brushed aluminium case shows how discreet and stylish a powerful PC can look.































INTEL GEN 11 CPU SUPPORT

COOLING

SUPPORT

HDMI 2.0b/1.4b 2x DISPLAY PORT

4K UHD SUPPORT

GRAPHICS Cards

SUPPORT

DUAL LAN

WLAN OPTIONAL

CUBE DESIGN

■ Black aluminium chassis ■ Dimensions: 33.2 x 21.5 x 19 cm (LWH), ca. 13.6-litre ■ Operating temperature: 0~40 °C (non-condensing)

OPERATING SYSTEM

- An operating system is not included
- Supports Windows 10 and Linux (64-bit)

PROCESSOR SUPPORT

■ Socket LGA1200 supports Intel Core i9/i7/i5/i3, Pentium Gold and Celeron processors of Gen. 10 "Comet Lake-S" and Gen. 11 "Rocket Lake-S" with up to 125W TDP ■ Includes heatpipe cooling system

CHIPSET & GRAPHICS

- Intel H570 Chinset
- Integrated Intel UHD graphics with triple 4K display support (features depend on processor, "F"-series CPUs lack the integrated graphics)

MEMORY SUPPORT

■ Four 288-pin DIMM slots ■ Supports up to 128 GB capacity in total (max. 32 GB each module) ■ Supports DDR4-2666/2933/3200

PCI-EXPRESS SLOTS

- 1x PCle X16 v3/v4 slot supports dual-slot graphics cards up to ca. 28 x 12 x 4 cm (LWH), with 6-pin and 8-pin power connector
- 1x PCIe X4 v3 slot (not usable with dual-slot graphics card)

STORAGE - SATA / M.2

- Bays: 4x 3.5" (internal), onboard: 4x SATA ports (supports RAID)
- 1x M.2-2280M slot (supports PCIe x4 v3/v4 NVMe or SATA)
- 1x M.2-2230E for optional WLAN (accessory: WLN-M)

CONNECTORS

- HDMI 1.4b/2.0b 2x DisplayPort 1.4 4x USB 3.2 Gen2 4x USB 3.2 Gen1 (1x Type-C) ■ 4x USB 2.0 ■ 1x internal USB 2.0 ■ 2x Intel Gigabit LAN (Intel i210AT+i219LM) ■ 5x Audio I/O (2x front, 3x rear)
- Connector for external power button

POWER SUPPLY

■ Internal 500W power supply, 80Plus Gold

OPTIONAL ACCESSORIES

■ WLAN-ac Kit (WLN-M) ■ RS232 COM Port (H-RS232) ■ Adapter for two 2.5" drives (PHD3) ■ Cable for external power button (CXP01)

Note: Some features market in red color are only supported in combination with Gen 11 "Rocket Lake-S" processors.

MODELS OF THE SH570 SERIES

Product	CPU Socket Chip Chassis Drive Bays		Power Supply	UPC Code		
SH570R6	LGA 1200	H570	R6	5.25" + 2x 3.5"	300 W, 80+ Bronze	887993003498
SH570R6 Plus	LGA 1200	H570	R6	5.25" + 2x 3.5"	500 W, 80+ Gold	887993003870
SH570R8	LGA 1200	H570	R8	4x 3.5"	500 W, 80+ Gold	887993003504

PRODUCT SPECIFICATIONS

REQUIRED COMPONENTS

The following components need to be added to make it a fully-configured Mini PC



LGA1200 Processor

Intel Core Gen 10 "Comet Lake-S" or Gen 11 "Rocket Lake-S" Core i9 / i7 / i5 / i3, Pentium Gold or Celeron TDP max. 125 W



Memory Modules

Up to four 288-pin DIMM memory modules, max. 32 GB each Supports DDR4-3200 clock rate with Gen 11 CPUs Supports DDR4-2933 clock rate with Core i7/i9 Gen 10 CPUs Supports DDR4-2666 clock rate with other Gen 10 CPUs



SATA Storage Drives The drive rack supports four 3.5" drives.

Note: use accessory PHD3 to install two 2.5" drives (Hard disks or SSDs) in a 3.5" bay. The mainboard features four SATA ports and one USB 2.0 onboard header.



Shuttle XPC Cube Barebone SH570R8

(Photo without chassis cover)



M.2 SSD (optional)

Supports M.2-2280/2260/2242 formats Supports SATA or PCIe/NVMe interfaces



PCI-EXPRESS CARDS (optional)

1) PCI-E X16 slot (e.g. Single-Slot graphics card) 2) PCI-E X4 slot (e.g. Dual 10 Gb network card) The power consumption of the graphics card must not exceed 300 watts [4]. Max. length is 273 mm. If a dual-slot (doublewidth) graphics cards is used the second PCI-Express slot will be occupied.



Operating System Windows 10 or Linux (64-bit only)

OPTIONAL ACCESSORIES FROM SHUTTLE



WLAN-Accessory WLN-M M.2-2230 card supports IEEE 802.11 b/g/n/ac including 2 antennas



Adapter for 2.5" drives

PHD3

The PHD3 allows for installation of one or two 63.5 mm (2.5") hard drives or SSDs into a larger 89 mm (3.5") drive bay.



COM Port Adapter

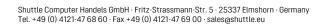
H-RS232

The H-RS232 allows for installation of one serial COM port (RS232) in the back panel.



Cable CXP01

Cable for external push button switch (without button)



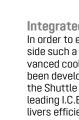
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PRODUCT FEATURES



The R8 chassis design: stylish and sophisticated

The R8 is the case design of choice when it comes to flexible storage solutions thanks to its four-hard-drive support. At the same time it provides an incredible amount of space for large state-of-the-art graphics cards. With no drive doors on the front, the case appears more uniform and elegant as ever before with Shuttle XPC cubes. Its high-quality finish and aesthetics remain untouched - the R8 case uses light aluminium as its stylish base material and the brushed surfaces are truly eye-catching.



Integrated Cooling Engine

In order to ensure proper airflow inside such a small case, more advanced cooling technologies have been developed and implemented in the Shuttle XPC. Shuttle's industryleading I.C.E. heatpipe technology delivers efficient cooling and is exceptionally quiet.



Ample space for demanding dual-slot graphics cards

Despite the small housing, the SH570R8 is capable of running dualslot (double-height) high-performance PCI Express graphics cards. The system provides additional 6-pin and 8pin power connectors for more power-hungry graphics cards. The maximum size acceptable for graphics cards is 273 mm x 98 mm x 38 mm. Please refer to the support list for detailed support information at global.shuttle.com.



Triple UHD display support and more

The integrated graphics supports up to three independent monitors at Ultra-HD resolution if not an F-type CPU

This XPC even supports at least five displays in combination with a discrete PCI-Express graphics card, based on the Switchable Graphics feature. Expand your Windows desktop across many monitors, but note it does not support a 2x2 configuration or clone mode with the monitors con-



What is a Barebone?

The Shuttle XPC cube Barebone SH570R8 consists of a stylish case with pre-installed mainboard, power supply unit (PSU) and cables. Despite its small form factor, it offers outstanding connectivity, functionality and performance. For a full PC system, a processor, memory, mass storage and operating system need to be added. Shuttle XPC cube Barebones are completely customisable meaning users can pick certain components on their own to ideally match their individual needs.



External power button by separate remote line

If, because of space constraints (e.g. in case of fixed installation), the machine cannot be switched on by pressing the front power button, it can be powered on by a separate remote line. You will find an appropriate four-pin connector at the back panel of the SH570R8 (pitch 2.54 mm). Furthermore, this connector provides a Clear CMOS function and +5V DC voltage supply for external devices.

+5V voltage (2) ● ● Clear CMOS (1) ■ ● Clear CMOS (1)



(4) Power Button (3) Ground

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Front and Back Panel

Front panel



- 1. Hard disk LED indicator
- 2. Power LED indicator
- 3. Power button
- 4. 3x USB 3.2 Gen 1 Type-A port (5 Gbps)
- 5. Microphone input
- 6. Headphones output
- 7. USB 3.2 Gen 1 Type-C port (5 Gbps)

Back panel



- 8. Internal power supply unit (PSU)
- 9. AC power connector
- 10. 3x perforation for optional WLAN antenna
- 11. Heat-pipe cooling system
- 12. Hole for Kensington Lock
- 13. Perforation for optional COM port
- 14. DisplayPort 1.4
- 15. 4-pin connector (2.54 mm pitch) for external power button, Clear CMOS button and 5V DC voltage
- 16. HDMI 2.0b/1.4b
- 17. 2x RJ45 Gigabit LAN port
- 18. 4x USB 2.0 port
- 19. 4x USB 3.2 Gen 2 Type-A port (10 Gbps)
- 20. Audio Line-in
- 21. Audio Line-out
- 22. Microphone input
- 23. PCI-Express X16 expansion slot
- 24. PCI-Express X4 expansion slot

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Mainboard



- 1. 3x Audio Ports (Line-in / Line-out / Microphone)
- 2. 4x USB 3.2 Gen 2 Type-A Port (10 Gbps)
- 3. 2x RJ45 Gigabit LAN port & 4x USB 2.0 port
- 4. HDMI 2.0b/1.4b port & DisplayPort 1.4
- 5. 4-pin connector (2.54 mm pitch) for external power button, Clear CMOS button and 5V DC voltage
- 6. DisplayPort 1.4
- 7. Front audio header
- 8. Debug header (reserved)
- 9. Onboard USB 2.0 connector (4-pin)
- 10. PCI-Express X4 expansion slot
- 11. PCI-Express X16 expansion slot
- 12. Onboard RS232 COM port header (2x5-pin)
- 13. Connector for cooling fan (4-pin)

- 14. Intel H570 chipset with heat sink
- 15. CMOS battery
- 16. CPU voltage regulator area
- 17. M2-2230E slot for WLAN card
- 18. M.2-2280M slot for SSD card
- 19. 4x SATA v3.0 connector
- 20. LGA1200 processor socket
- 21. 4x DIMM memory slot
- 22. Connector for cooling fan (4-pin)
- 23. Front USB 3.0 header
- 24. Front buttons / LEDs header
- 25. ATX power connector (20-pin)
- 26. ATX power connector (4-pin)



Shuttle Product Comparison: SH3xx versus SH5xx

The differences in the newer SH5xx series are marked in red.

MODEL	SH310R4V2	SH370R6V2 (PLUS)	SH370R8	SH510R4	SH570R6 (PLUS)	SH570R8		
CHASSIS	R4 chassis with customisable front plate	R6 chassis with front doors for I/O ports	R8 chassis supports four 3.5" hard disks	R4 chassis with customisable front plate	R6 chassis with front doors for I/O ports	R8 chassis supports four 3.5" hard disks		
PROCESSOR SUPPORT		t LGA1151v2, TDP max e Lake-S (Refresh)" 14		Socket LGA1200, TDP max. 125 W Code name "Comet/Rocket Lake-S" 14 nm – Gen 10/11				
CHIPSET	Intel H310	Intel H370	Intel H370	Intel H510	Intel H570	Intel H570		
OS SUPPORT	Wind	lows 10 and Linux (64	1-bit)	Wind	Windows 10 and Linux (64-bit)			
DRIVE BAYS	1x 5.25" 2x 3.5"	1x 5.25" 2x 3.5" (1x open)	4x 3.5"	1x 5.25" 2x 3.5"	1x 5.25" 2x 3.5" (1x open)	4x 3.5"		
SATA PORTS	3	4	4	3	4	4		
PCI-E SLOTS	1x PCIe X16 v3.0 1x PCIe X1 V2.0	1x PCIe X16 v3.0 1x PCIe X4 V3.0	1x PCle X16 v3.0 1x PCle X4 V3.0	1x PCle X16 v4.0 1x PCle X1 V2.0	1x PCle X16 v4.0 1x PCle X4 V3.0	1x PCle X16 v4.0 1x PCle X4 V3.0		
MAX. RAM SUPPORT	2x 16 GB DDR4-2666/2933	4x 32 GB DDR4-2666/2933	4x 32 GB DDR4-2666/2933	2x 32 GB DDR4-3200 [1]	4x 32 GB DDR4-3200 [1]	4x 32 GB DDR4-3200 [1]		
GRAPHICS PORTS	HDMI 2.0a DP 1.2, VGA	HDMI 2.0a 2x DP 1.2	HDMI 2.0a 2x DP 1.2	HDMI 2.0b [1] DP 1.4, VGA	HDMI 2.0b [1] 2x DP 1.4	HDMI 2.0b [1] 2x DP 1.4		
M.2 SSD SLOT	M.22280M	(supports SATA / NVI	Me PCIe X4)	M.22280M	(supports SATA / NVI	Me PCIe X4)		
WLAN SLOT		M.2-2230E			M.2-2230E			
BUTTONS / LEDS	Power-	Button, Power LED, H	IDD LED	Power-	Button, Power LED, H	DD LED		
USB 3.2 GEN 2 (10G)	_	4	4	-	4	4		
USB 3.2 GEN 1 (5G)	4	4	4	4	4 (1x Type-C)	4 (1x Type-C)		
USB 2.0	4	4	4	4	4	4		
USB 2.0 ONBOARD	1	2	2	1	1	1		
GIGABIT NETWORK	Single LAN Intel i219LM	Dual LAN 2x Intel 211	Dual LAN 2x Intel 211	Single LAN Intel i219LM	Dual LAN 1x Intel i210AT 1x Intel i219LM	Dual LAN 1x Intel i210AT 1x Intel i219LM		
AUDIO	Mic-Input, Head	ohone Output and 6-c	channel Line-Out	Mic-Input, Headphone Output and 6-channel Line-Out				
OPTIONAL ACCESSORIES	3	WLAN Kit: WLN-M COM-Port: H-RS232 5"/2.5" Adapter: PHE	03	WLAN Kit: WLN-M COM-Port: H-RS232 3.5"/2.5" Adapter: PHD3 Cable for ext. power button: CXP01				
POWER SUPPLY	300W 80+ Bronze	Standard: 300W Plus: 500W	500 W 80+ Gold	300W 80+ Bronze	Standard: 300W Plus: 500W	500 W 80+ Gold		

[1] Note: SH5xx-Series supports PCIe X16 V4 slot, DDR4-3200 and HDMI 2.0b with Gen. 11 Processors "Rocket Lake-S", but only PCIe X16 V3 slot, DDR4-2666/2933 and HDMI 1.4b with Gen. 10 Processors "Comet Lake-S".



SHUTTLE XPC CUBE BAREBONE SH570R8 — SPECIFICATIONS

CHASSIS	Black aluminium chassis Front panel: brushed aluminium Front door for I/O ports (USB and Audio) Kensington Security Slot at the backpanel (also called K-Slot or Kensington lock) as a part of an anti-theft system Dimensions: 33.2 x 21,5 x 19.0 cm (LWH without feet) = 13.6 litre Height with rubber feet: 19.7 cm Weight: 3.5 kg net / 4.5 kg gross
MAINBOARD / CHIPSET	Mainboard with Shuttle form factor, proprietary design for XPC SH570R8 Chipset/Southbridge: Intel® H570 Passive chipset cooling with heat sink The Northbridge is integrated in the processor. Solid Capacitors for sensitive areas provide excellent heat resistance for enhanced system durability
BIOS	AMI BIOS, SPI Interface, 16 MB Flash-EEPROM Supports Hardware Monitoring, Watch Dog Supports Power Fail Resume Supports Firmware-TPM (fTPM) v2.0 Supports boot up from external USB flash memory Supports Unified Extensible Firmware Interface (UEFI)
POWER SUPPLY	Built-in 500 Watt mini switching power supply [4] AC input voltage: 100~240V, 50~60 Hz 80 PLUS Gold compliant Active PFC circuit (Power Factor Correction) ATX main power connectors: 2x10 and 2x2-pin Graphics power connector: 6-pin and 8-pin Other connectors: 4x SATA, 2x Molex
OPERATING SYSTEM	This system comes without operating system. It is compatible with Windows 10 and Linux (64-bit)
PROCESSOR SUPPORT	Processor Socket LGA 1200 Supports Intel Core i9 / i7 / i5 / i3, Pentium Gold and Celeron processors Supports the 10th and 11th generation Intel Core processors, code name "Comet Lake-S" and "Rocket Lake-S" in 14++ nm process technology Maximum supported processor power consumption (TDP) = 125 W Up to 10 CPU cores, 20 threads and 20 MB of L3 cache Does not support the unlock-function of Intel K-Series processors. The processor integrates PCI-Express, memory controller and the graphics engine on the same die. However, processors with "F" identifier do not support integrated graphics [2] (performance features depending on processor type) Please refer to the support list for detailed processor support information at global.shuttle.com.
HEAT-PIPE COOLING	Shuttle I.C.E. (Integrated Cooling Engine) advanced I.C.E. heatpipe technology, linear-controlled 92mm fan SilentX cooling and noise reduction technology with Active Airflow
MEMORY SUPPORT	4x 288-pin slot Supports DDR4 memory at 1.2V Supports Dual Channel mode Supports max. 32 GB per DIMM, maximum total size of 128 GB The maximum DDR4 clock frequency depends on the processor type used: - Gen. 11 "Rocket Lake" supports DDR4-3200 (PC4-25600U) - Gen. 10 "Comet Lake" Core i7/i9 supports DDR4-2933 (PC4-23433U) - other Gen. 10 "Comet Lake" support DDR4-2666 (PC4-21300U)
PCI-E EXPANSION SLOTS	1x PCI-Express x16 v4.0 slot (supports PCI-Express v3.0 with Gen. 10 "Comet Lake" processors) 1x PCI-Express x4 v3.0 slot, open-ended Supports dual-slot (double-width) graphics cards (occupies the second PCI-Express slot) The maximum size acceptable for display cards is 273 x 98 x 38 mm. Graphics power connector: 6-pin and 8-pin [4]



INTEGRATED GRAPHICS (OPTIONAL [2])	The features of the integrated Intel UHD graphics function depend on the processor type used. Certain processor models do not support integrated graphics [2] The PC features three video outputs which support 2160p/60 UHD resolution: - 1x HDMI v2.0b (only HDMI v1.4b with Gen. 10 "Comet Lake" Prozessoren) - 2x DisplayPort v1.4 Supports displays with 4K Ultra HD resolution at 3840 x 2160 (2160p/60) Supports three independent displays with the integrated graphics function Supports more displays in combination with a discrete graphics card Hardware video decoding/encoding DisplayPort and HDMI support multi-channel digital audio over the same cable
DRIVE BAYS	Storage bays: 4x 3.5" (internal) Using the optional accessory PHD3 two 2.5" drives can be installed into one 3.5" bay.
SATA CONNECTORS	4x Serial ATA 6G connector onboard (rev. 3.0, max. 6 Gbit/s) Supports Intel Rapid Storage Technology (RST) with RAID 0/1/5/10, JBOD)
M.2-2280M SSD SLOT	The M.2 2280M slot provides the following interfaces: - PCI-Express Gen. 4.0 X4, supports NVMe (supports only PCI-Express Gen 3.0 X4 with Gen. 10 "Comet Lake-S CPU) - SATA v3.0 (max. 6 Gbps) It supports M.2 cards with a width of 22 mm and a length of 42, 60 or 80 mm (type 2242, 2260, 2280). Supports M.2 SSDs with SATA or PCI-Express interface
M.2-2230E SLOT FOR WLAN CARDS	Interfaces: PCI-Express Gen. 3.0 X1 und USB 2.0 Supports M.2 cards with a width of 22 mm and a length of 30 mm (type 2230) Supports WLAN extension cards (optional Shuttle accessory: WLN-M)
HD AUDIO	Audio Codec: Realtek ALC897, 5.1 channel Three analog audio connectors (3.5 mm) on the backpanel: Line-in (blue), line-out (green) and microphone input (pink) shared with 5.1 channel line-out (front, rear, center/bass) Front panel: microphone input and head phone output (line-out)
DUAL GIGABIT LAN	Dual Gigabit network with two RJ45 ports 1x Intel i210AT - Ethernet Controller with MAC, PHY and PCIe interface 1x Intel i219LM - PHY connected to the MAC of the processor Supports 10 / 100 / 1.000 MBit/s operation Supports WAKE ON LAN (WOL) Supports network boot by Preboot eXecution Environment (PXE) Supports Teaming mode [3]
FRONT PANEL CONNECTORS	Microphone input (3.5 mm) Headphones output (3.5 mm) 1x USB 3.2 Gen 1 (5 Gbps), Type C 3x USB 3.2 Gen 1 (5 Gbps), Type A, blue Power button Power indicator (Blue LED) Hard disk drive indicator (Yellow LED)
BACK PANEL CONNECTORS	1x HDMI 2.0b (HDMI 1.4b with Gen. 10 "Comet Lake" processor) 2x DisplayPort 1.4 [1] 4x USB 3.2 Gen 2 (10 Gbps), Type A, red 4x USB 2.0 (Type A, black) 2x Gigabit LAN (RJ45) Audio Line-out (3.5 mm) Audio Line-in (3.5 mm) Microphone Input (3.5 mm) 1x 4-pin connector (2.54 mm pitch) supports: - external power on button - Clear CMOS function - +5V DC voltage for external components Optional: Serial RS232 port (Accessory: "H-RS232") 3x perforation for optional WLAN antennas (Accessory: "WLN-M")





OTHER ONBOARD CONNECTORS	Occupied front panel connectors for USB, audio, buttons, LEDs 1x RS232 serial interface (2x5 pin header) 2x fan connectors (4-pin header) 1x USB 2.0 (4-pin header)
SUPPLIED ACCESSORIES	Multi-language XPC Installation Guide (EN, DE, FR, ES, JP, KR, SC, TC) Windows 64-bit driver disk 2x Serial ATA cables AC Power Cord (with protective-earth contacts) Heatsink Compound Protector cap for the CPU socket (do not use if heatpipe or fan is mounted) Bag with screws
OPTIONAL ACCESSORIES	Back panel adapter for serial RS232 port (H-RS232) WLAN IEEE 802.11ac/BT4.2 kit with two external antennas (WLN-M) Adapter for 2.5" drives such as SSDs (PHD3) Adapter cable for external power button (CXP01)
ENVIRONMENTAL SPECIFICATIONS	Permissible ambient temperature during operation: 0~40 °C Relative humidity: 10~90 %.
CERTIFICATIONS / COMPLIANCE	EMI: FCC, CE, BSMI, C-Tick Safety: ETL, CB, BSMI Other: RoHS, Energy Star 5.0, ErP This device is classed as a technical information equipment (ITE) in class B and is intended for use in living room and office. The CE-mark approves the conformity by the EU directives: (1) 2014/30/EU relating to electromagnetic compatibility (EMC), (2) 2014/35/EU relating to Electrical Equipment designed for use within certain voltage limits (LVD), (3) 2009/125/EC relating to ecodesign requirements for energy-related products (ErP).

[1] How to convert DisplayPort to HDMI/DVI

The DisplayPort output can be converted to HDMI or DVI by an additional, passive adapter cable. For example:

DELOCK 82590: 1 m, DisplayPort (male, 20p) to HDMI-A (male, 19p)

DELOCK 82435: 5 m, DisplayPort (male, 20p) to DVI-D (male, 24p)

The integrated graphics automatically detects the connected display and puts out the appropriate electric signal - either DisplayPort (without an adapter) or HDMI/DVI (with an adapter).

However, a monitor with a DisplayPort connector cannot be connected to the HDMI port with a simple, passive adapter.

[2] Integrated graphics is optional

Processors with model numbers ending with "F" (z.B. Intel Core i5-11600F) do not support integrated graphics, so that the graphics outputs of the Shuttle XPC have no function. In this case, an additional an additional discrete PCIe graphics card is mandatory.

[3] Teaming Mode

The teaming function allows you to group both available network adapters together to function as a single adapter. The benefit of this approach is that it enables load balancing and failover.

[4] Online Power Calculator

The PCI Express x16 slot provides a maximum of 75 Watts to the graphics card, plus 75 Watts and 150 Watts from the 6-pin and 8-pin connector of the power supply - so the power consumption of the graphics card must not exceed 300 watts. The processor may have a maximum TDP of 125 Watts. If powerful PC components are used, then check with the "Power Supply Calculator" whether the built-in 500 Watt power supply supports this configuration, see: http://global.shuttle.com/support/power. Please also refer to the support list for detailed processor and graphics cards support information at http://global.shuttle.com.



10TH GENERATION INTEL CORE DESKTOP PROCESSOR FAMILY

Socket LGA1200 14 nm "Comet Lake S" processor overview (Date: June 2021)

PROCESSOR	MODEL	CORES/ THREADS	CPU CLOCK	TURBO BOOST CLOCK (2.0)	SMART CACHE	TDP	MEMORY Support	GRAPHICS ENGINE MAX. CLOCK
Core™ i9	10900 <mark>K</mark>	10/20	3.7 GHz	5.1 GHz	20 MB	125 W	DDR4-2933	UHD 630 (1.2 GHz)
	10900 <mark>K</mark> F	10/20	3.7 GHz	5.1 GHz	20 MB	125 W	DDR4-2933	None
	10910	10/20	3.6 GHz	5.0 GHz	20 MB	125 W	DDR4-2933	UHD 630 (1.2 GHz)
	10900	10/20	2.8 GHz	5.0 GHz	20 MB	65 W	DDR4-2933	UHD 630 (1.2 GHz)
	10900F	10/20	2.8 GHz	5.0 GHz	20 MB	65 W	DDR4-2933	None
	10900T	10/20	1.9 GHz	4.5 GHz	20 MB	35 W	DDR4-2933	UHD 630 (1.2 GHz)
	10850 <mark>K</mark>	10/20	3.6 GHz	5.0 GHz	20 MB	125 W	DDR4-2933	UHD 630 (1.2 GHz)
	10700 <mark>K</mark>	8/16	3.8 GHz	5.0 GHz	16 MB	125 W	DDR4-2933	UHD 630 (1.2 GHz)
	10700 <mark>K</mark> F	8/16	3.8 GHz	5.0 GHz	16 MB	125 W	DDR4-2933	None
Core™ i7	10700	8/16	2.9 GHz	4.7 GHz	16 MB	65 W	DDR4-2933	UHD 630 (1.2 GHz)
	10700F	8/16	2.9 GHz	4.7 GHz	16 MB	65 W	DDR4-2933	None
	10700T	8/16	2.0 GHz	4.4 GHz	16 MB	35 W	DDR4-2933	UHD 630 (1.2 GHz)
	10600 <mark>K</mark>	6/12	4.1 GHz	4.8 GHz	12 MB	125 W	DDR4-2666	UHD 630 (1.2 GHz)
	10600 K F	6/12	4.1 GHz	4.8 GHz	12 MB	125 W	DDR4-2666	None
	10600	6/12	3.3 GHz	4.8 GHz	12 MB	65 W	DDR4-2666	UHD 630 (1.2 GHz)
	10600T	6/12	2.4 GHz	4.0 GHz	12 MB	35 W	DDR4-2666	UHD 630 (1.2 GHz)
Core™ i5	10500	6/12	3.1 GHz	4.5 GHz	12 MB	65 W	DDR4-2666	UHD 630 (1.15 GHz)
	10500T	6/12	2.3 GHz	3.8 GHz	12 MB	35 W	DDR4-2666	UHD 630 (1.1 GHz)
	10400	6/12	2.9 GHz	4.3 GHz	12 MB	65 W	DDR4-2666	UHD 630 (1.1 GHz)
	10400F	6/12	2.9 GHz	4.3 GHz	12 MB	65 W	DDR4-2666	None
	10400T	6/12	2.0 GHz	3.6 GHz	12 MB	35 W	DDR4-2666	UHD 630 (1.10 GHz)
	10320	4/8	3.8 GHz	4.6 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.15 GHz)
	10300	4/8	3.7 GHz	4.4 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.15 GHz)
Corolli (2	10300T	4/8	3.0 GHz	3.9 GHz	8 MB	35 W	DDR4-2666	UHD 630 (1.1 GHz)
Core™ i3	10100	4/8	3.6 GHz	4.3 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.1 GHz)
	10100F	4/8	3.6 GHz	4.3 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.1 GHz)
	10100T	4/8	3.0 GHz	3.8 GHz	8 MB	35 W	DDR4-2666	UHD 630 (1.1 GHz)
	G6600	2/4	4.2 GHz	-	4 MB	58 W	DDR4-2666	UHD 630 (1.1 GHz)
	G6500	2/4	4.1 GHz	_	4 MB	58 W	DDR4-2666	UHD 630 (1.1 GHz)
Pentium® Gold	G6500T	2/4	3.5 GHz	-	4 MB	35 W	DDR4-2666	UHD 630 (1.05 GHz)
oota	G6400	2/4	4.0 GHz	_	4 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G6400T	2/4	3.4 GHz	-	4 MB	35 W	DDR4-2666	UHD 610 (1.05 GHz)
Celeron®	G5925	2/2	3.6 GHz	-	4 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5920	2/2	3.5 GHz	-	2 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5905	2/2	3.5 GHz	-	4 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5905T	2/2	3.3 GHz	-	4 MB	35 W	DDR4-2666	UHD 610 (1.0 GHz)
	G5900	2/2	3.4 GHz	_	2 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5900T	2/2	3.2 GHz	-	2 MB	35 W	DDR4-2666	UHD 610 (1.05 GHz)

K = unlocked, T = Power optimized lifestyle, F = without integrated graphics, TDP = Thermal Design Power (max. Power Consumption).

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11TH GENERATION INTEL CORE DESKTOP PROCESSOR FAMILY

Socket LGA1200 14 nm "Rocket Lake S" processor overview (Date: June 2021)

PROCESSOR	MODEL	CORES/ THREADS	CPU CLOCK	TURBO BOOST CLOCK (2.0)	SMART CACHE	TDP	MEMORY SUPPORT	GRAPHICS ENGINE MAX. CLOCK / EUs
	11900 <mark>K</mark>	8/16	3.5 GHz	5.3 GHz	16 MB	125 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11900 <mark>K</mark> F	8/16	3.5 GHz	5.3 GHz	16 MB	125 W	DDR4-3200	None
Core™ i9	11900	8/16	2.5 GHz	5.2 GHz	16 MB	65 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11900F	8/16	2.5 GHz	5.2 GHz	16 MB	65 W	DDR4-3200	None
	11900T	8/16	1.5 GHz	4.9 GHz	16 MB	35 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11700 <mark>K</mark>	8/16	3.6 GHz	5.0 GHz	16 MB	125 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11700 <mark>K</mark> F	8/16	3.6 GHz	5.0 GHz	16 MB	125 W	DDR4-3200	None
Core™ i7	11700	8/16	2.5 GHz	4.9 GHz	16 MB	65 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11700F	8/16	2.5 GHz	4.9 GHz	16 MB	65 W	DDR4-3200	None
	11700T	8/16	1.4 GHz	4.6 GHz	16 MB	35 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11600 <mark>K</mark>	6/12	3.9 GHz	4.9 GHz	12 MB	125 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11600 <mark>K</mark> F	6/12	3.9 GHz	4.9 GHz	12 MB	125 W	DDR4-3200	None
	11600	6/12	2.8 GHz	4.8 GHz	12 MB	65 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11600T	6/12	1.7 GHz	4.1 GHz	12 MB	35 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
Core™ i5	11500	6/12	2.7 GHz	4.6 GHz	12 MB	65 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11500T	6/12	1.5 GHz	3.9 GHz	12 MB	35 W	DDR4-3200	UHD 750 (1.2 GHz, 32 EUs)
	11400	6/12	2.6 GHz	4.4 GHz	12 MB	65 W	DDR4-3200	UHD 730 (1.3 GHz, 24 EUs)
	11400F	6/12	2.6 GHz	4.4 GHz	12 MB	65 W	DDR4-3200	None
	11400T	6/12	1.3 GHz	3.7 GHz	12 MB	35 W	DDR4-3200	UHD 730 (1.2 GHz, 24 EUs)

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